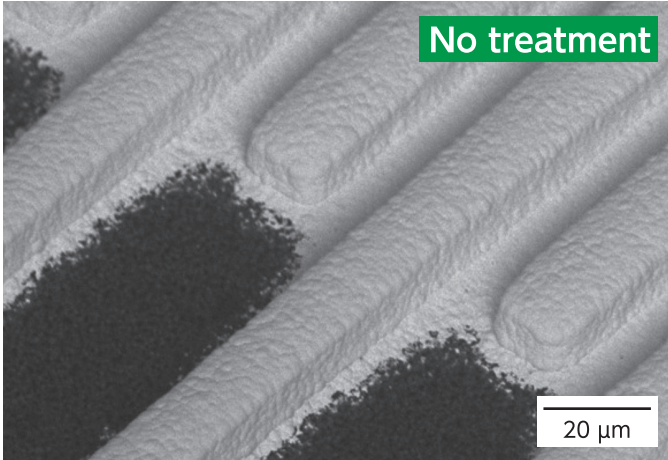


# Cyanide-free palladium residue remover

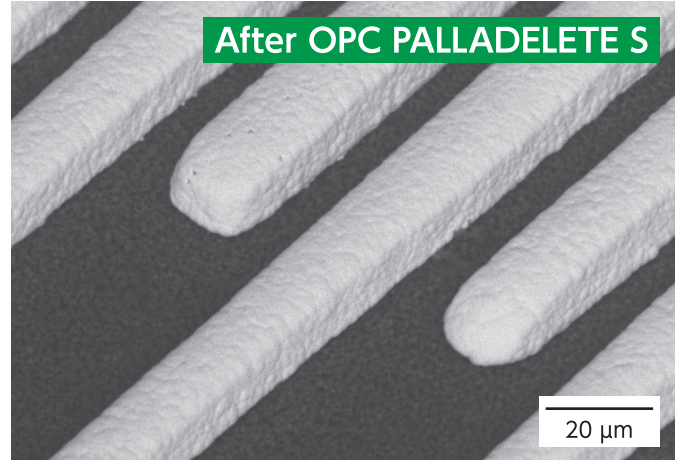
## OPC PALLADELETE S

SAP

- Cyanide-free process
- Weak alkaline type, reduce attack to substrates
- Can remove palladium residues among fine patterns
- Prevent copper pattern dissolution strongly (Below 0.05  $\mu\text{m}$ )
- Can control by bath analysis



No treatment



After OPC PALLADELETE S

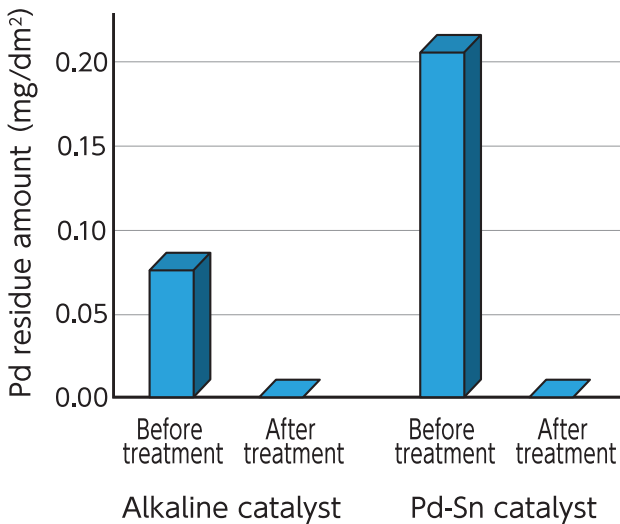
Electrolerss Ni plating:3  $\mu\text{m}$ , immersion Au plating:0.05  $\mu\text{m}$

Deposition out of patterns

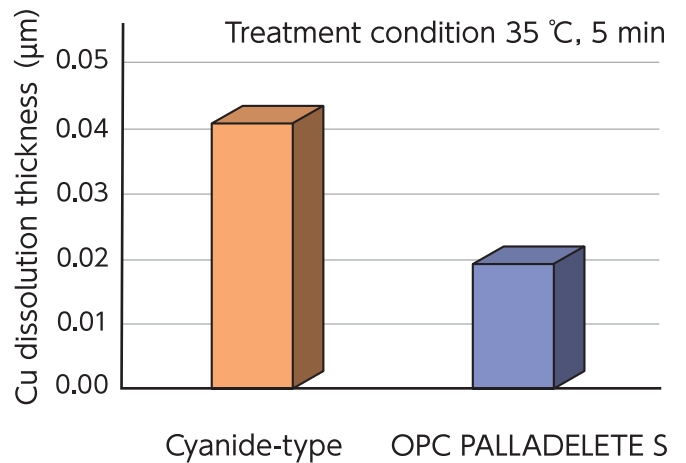
No deposition out of patterns

Strongly remove Pd residues

Reduce Cu dissolution



Applicable to Pd-Sn catalyst



Applicable to fine patterning